

**MAPC-C22650-DP** 

Rev. V1

## MACOM PURE CARBIDE

#### **Features**

- GaN on SiC HEMT Technology
- Designed for Asymmetrical Doherty Application
- Average Output Power: 48.8 dBm
- Peak Output Power: 500 W
- Input and Output Pre-matched Device
- Low Thermal Resistance
- 100% DC and RF Tested
- RoHS\* Compliant

## **Applications**

Infrastructure

#### Description

The MAPC-C22650-DP is a GaN on Silicon Carbide HEMT Amplifier designed for asymmetrical Doherty applications. The device is optimized for the frequency band of 1805 to 2170 MHz. This product is housed in an over-molded TO-package.

### **Typical Doherty Performance:**

 $V_{DS}$  = 52 V,  $I_{DQm}$  = 250 mA,  $V_{GSpk}$ =  $V_{GSpk}$ (500 mA) - 3.05 V,  $P_{OUT}$  = 48.8 dBm,  $T_A$  = 25°C

Frequency (MHz)	Gain (dB)	Efficiency (%)	Output PAR (dB)	ACPR (dBc)
1805	16.8	56.4	9.03	- 24.6
1880	17.1	56.5	9.28	- 28.0
2110	17.0	57.2	8.85	- 31.3
2170	16.4	59.4	8.37	- 30.6

Note:

Performance in MACOM Doherty Application Fixture. Single Carrier W-CDMA Channel Bandwidth 3.84 MHz, PAR 10 dB @ 0.01% CCDF.

### **Ordering Information**

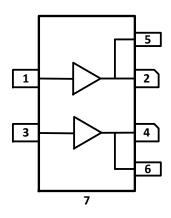
Part Number	Package
MAPC-C22650-DPTR1	250 pc Tape and Reel <sup>1</sup>
MAPC-C22650-DPTR2	50 pc Tape and Reel <sup>1</sup>
MAPC-C22650-DPSB1	Sample Board

1. See application note AN-0004525 for Tape & Reel information.



TO-248-4/2

### **Functional Schematic**



## **Pin Configuration**

Pin#	Pin Name	Function
1	RF <sub>IN</sub> / V <sub>G1</sub>	RF Input / Gate (Main)
2	RF <sub>OUT</sub> / V <sub>D1</sub>	RF Output / Drain (Main)
3	RF <sub>IN</sub> / V <sub>G2</sub>	RF Input / Gate (Peak)
4	RF <sub>OUT</sub> / V <sub>D2</sub>	RF Output / Drain (Peak)
5, 6	VBW Lead	Drain Video Decoupling. No DC Bias
7	Flange <sup>2</sup>	Ground / Source

The flange on the package bottom must be connected to RF, DC and thermal ground.

<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

# High Power RF GaN Amplifier 500 W, 52 V, 1805 - 2170 MHz



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#### **RF Electrical Characterization:**

Freq. = 2170 MHz,  $P_{OUT}$  = 48.8 dBm,  $T_A$  = 25°C,  $V_{DS}$  = 52 V,  $I_{DQm}$  = 250 mA,  $V_{GSpk}$ =  $V_{GSpk}$ (500 mA) - 3.05 V Performance in MACOM Doherty Application Fixture. Single Carrier-W-CDMA Channel Bandwidth 3.84 MHz, PAR 10 dB @ 0.01% CCDF.

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Power Gain	_	Gp	_	16.4	_	dB
Drain Efficiency	_	η	_	59.4	_	%
Output CCDF @ 0.01%	_	PAR	_	8.37	_	dB
Adjacent Channel Power	_	ACP	_	- 30.6	_	dBc
Input Return Loss	_	IRL	_	- 19	_	dB
Gain Flatness	_	G <sub>F</sub>	_	0.7	_	dB
Gain Variation (-40°C to +105°C)	2170 MHz, -40°C to +105°C	ΔG	_	- 0.0126	_	dB/°C
Power Variation (-40°C to +105°C)	2170 MHz, -40°C to +105°C, Pulsed 10% DC	$\Delta P_{3dB}$	_	- 0.0044	_	dB/°C
Ruggedness: Output Mismatch All phase angles		Ψ	VSWR	e =10:1,No	Device Da	amage

## **RF Electrical Test Specifications:**

P<sub>OUT</sub> = 48.8 dBm, T<sub>A</sub> = 25°C, V<sub>DS</sub> = 48 V, I<sub>DQm</sub> = 250 mA, V<sub>GSpk</sub>= V<sub>GSpk</sub>(500 mA) - 3.05 V Performance in MACOM Doherty Production Test Fixture. Single Carrier- W-CDMA Channel Bandwidth 3.84MHz, PAR 10dB @ 0.01% CCDF.

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Danier Oair	Freq. = 1805 MHz	5	13.5	15.3	_	- dB
Power Gain	Freq. = 2170 MHz	- Gp	14.0	15.3	_	
Drain Efficiency	Freq. = 1805 MHz	_	51.0	55.2	_	%
	Freq. = 2170 MHz	η	53.0	58.5	_	
Output CCDF @ 0.01%	Freq. = 1805 MHz	PAR	6.3	7.1	_	dB
	Freq. = 2170 MHz	PAR	5.7	6.7	_	иБ
Adjacent Channel Power	Freq. = 1805 MHz	ACP	_	- 23.8	- 21.5	dBc
	Freq. = 2170 MHz	ACP	_	- 26.8	- 22.5	ubc



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## DC Electrical Characteristics T<sub>A</sub> = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units	
Main Amplifier							
Drain-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 10 V	I <sub>DLK</sub>	_	_	3.5	mA	
Drain-Source Leakage Current	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 130 V	I <sub>DLK</sub>	_	_	7.0	mA	
Gate-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 50 V	I <sub>GLK</sub>	- 5.7	_	_	mA	
Gate-Source Leakage Current	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 130 V	I <sub>GLK</sub>	- 3.0	_	_	mA	
Gate Threshold Voltage	$V_{DS} = 10 \text{ V}, I_{D} = 25 \text{ mA}$	V <sub>T</sub>	- 3.5	- 2.3	- 1.7	V	
	Peak Amplifier						
Drain-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 10 V	I <sub>DLK</sub>	_	_	7.0	mA	
Drain-Source Leakage Current	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 130 V	I <sub>DLK</sub>	_	_	14.1	mA	
Gate-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 50 V	I <sub>GLK</sub>	- 11.3	_	_	mA	
Gate-Source Leakage Current	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 130 V	I <sub>GLK</sub>	- 6.1	_	_	mA	
Gate Threshold Voltage	$V_{DS} = 10 \text{ V}, I_{D} = 50 \text{ mA}$	V <sub>T</sub>	- 3.5	- 2.2	- 1.7	V	

# **Recommended Operating Voltages**

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Drain Operating Voltage	_	V	_	52	
Gate Quiescent Voltage	V <sub>DS</sub> = 52 V, I <sub>D</sub> = 250 mA	V	- 3.5	- 2.2	- 1.9

# **Moisture Sensitivity Level**

Level	Test Standard	Package Temperature	Unit
3	IPC/JEDEC J-STD-020	260	°C



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# **Absolute Maximum Ratings**<sup>3,4,5,6,7</sup>

Parameter	Absolute Maximum
Drain Source Voltage, V <sub>DS</sub>	100 V
Operating Voltage, V <sub>DS</sub>	55 V
Gate Source Voltage, V <sub>GS</sub>	- 10 to 2 V
Gate Current (Main), I <sub>G</sub>	25 mA
Gate Current (Peak), I <sub>G</sub>	50 mA
Storage Temperature Range	- 65°C to +150°C
Case Operating Temperature Range	- 40°C to +125°C
Channel Operating Temperature Range, T <sub>CH</sub>	- 40°C to +225°C
Absolute Maximum Channel Temperature	+225°C

<sup>3.</sup> Exceeding any one or combination of these limits may cause permanent damage to this device.

4. MACOM does not recommend sustained operation above maximum operating conditions.

## Thermal Characteristics<sup>8</sup>

Parameter	Test Conditions	Symbol	Typical	Units
Thermal Resistance using Finite Element Analysis, T <sub>J</sub>	P <sub>DISS</sub> = 84 W T <sub>C</sub> = 116°C,T <sub>CH</sub> = 225°C	$R_{\theta}(FEA)$	1.3	°C/W
Thermal Resistance using Infrared Measurement of Die Surface Temperature		$R_{\theta}(IR)$	1.0	°C/W

<sup>8.</sup> Case temperature measured using thermocouple embedded in heat-sink. Contact local applications support team for more details on this measurement.

#### Bias Sequencing **Bias ON**

- 1. Ensure RF is turned off
- 2. Apply pinch-off voltage of -5 V to the gate
- 3. Apply nominal drain voltage
- 4. Bias gate to desired quiescent drain current
- 5. Apply RF

#### **Bias OFF**

- 1. Turn RF off
- 2. Apply pinch-off voltage to the gate
- 3. Turn-off drain voltage
- 4. Turn-off gate voltage

#### **Handling Procedures**

Please observe the following precautions to avoid damage:

#### Static Sensitivity

Gallium Nitride Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

<sup>5.</sup> Operating at drain source voltage  $V_{DS}$  < 55V will ensure MTTF > 2.51 x 10<sup>6</sup> hours.

 <sup>6.</sup> Operating at nominal conditions with T<sub>CH</sub> ≤ 225°C will ensure MTTF > 2.51 x 10<sup>6</sup> hours.
7. MTTF may be estimated by the expression MTTF (hours) = A e <sup>[B + C/(T+273)]</sup> where *T* is the channel temperature in degrees Celsius., A = 1.93, B = -45.31, and C = 29,585.

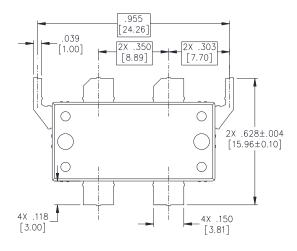


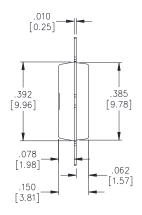
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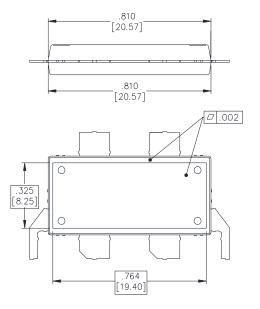
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## TO-248-4/2 Package Dimensions







#### NOTES:

- ALL DIMENSIONS SHOWN AS in[mm]. CONTROLLING DIMENSIONS ARE IN in AND CONVERTED mm DIMENSIONS ARE NOT NECESSARILY EXACT.
- 2. ALL TOLERANCES ARE ±.002 [0.05] UNLESS OTHERWISE NOTED.
- ALL METAL SURFACES ARE MATTE Sn PLATED EXCEPT FOR CUT EDGES.
- 4. PACKAGE BODY AND LEAD DIMENSIONS DO NOT INCLUDE MOLD AND METAL PROTRUSIONS. ALLOWABLE PROTRUSION IS .012 [0.30] IN GENERAL AND .004 [0.10] FOR PROTRUSIONS CONNECTED TO SOURCE

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